

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (Currently Amended): A system of coinsurance wafer management for use in MPW (multi-project wafer) shuttle service, comprising at least:

a production line to process at least a MPW shuttle including a plurality of original wafers and a quantity of coinsurance wafers with a common fabrication process before metal layering, process the original wafers with different metal layering fabrication processes according to a metal layering technology of each device design of the MPW shuttle, and withhold the coinsurance wafers without further fabrication,

wherein the production line releases at least one of the coinsurance wafers to replace each original wafer scrapped in the common fabrication process.

2. (Original): The system of claim 1 wherein the MPW shuttle is split into a plurality of child lots according to the metal layering technology of each device design of the MPW shuttle when the common fabrication process is complete, in which one child lot comprises the coinsurance wafers, and the other child lots are processed with different metal layering fabrication processes.

3. (Canceled).

4. (Original): The system of claim 1 wherein the production line further releases at least one of the coinsurance wafers, and processes it with the metal layering fabrication process corresponding to each original wafer scrapped in the metal layering fabrication process.

5. (Original): The system of claim 1 further comprising a delivery unit to deliver respective products of each device design fabricated from the original wafers to corresponding clients.

6. (Original): The system of claim 1 further comprising an order management unit to receive a request for at least one designated device design of the device designs after the metal layering fabrication processes.

7. (Original): The system of claim 6 wherein the request is received before a cutoff date of the MPW shuttle.

8. (Original): The system of claim 6 wherein the production line further releases at least one coinsurance wafer for processes with the corresponding metal layering fabrication process when the request is received.

9. (Original): The system of claim 1 further comprising a transmission unit to transfer information of the coinsurance wafers to clients via a network.

10. (Original): The system of claim 9 wherein the transmission unit further transfers information of the original wafers corresponding to the respective device designs to the corresponding clients.

11. (Original): The system of claim 1 wherein the metal layering technology is the number of metal layers of each device design.

12. (Original): The system of claim 1 further comprising a determination unit to determine the quantity of coinsurance wafers according to a scrapping rate and the quantity of the original wafers.

13. (Currently Amended): A method of coinsurance wafer management for use in MPW (multi-project wafer) shuttle service, comprising the steps of:

processing at least one MPW shuttle with a common fabrication process before metal layering, in which the MPW shuttle includes a plurality of original wafers and a quantity of coinsurance wafers;

processing the original wafers with different metal layering fabrication processes according to a metal layering technology of each device design of the MPW shuttle; and

withholding the coinsurance wafers without further fabrication; and

releasing at least one of the coinsurance wafers to replace each original wafer scrapped in the common fabrication process.

14. (Original): The method of claim 13 further comprising splitting the MPW shuttle into a plurality of child lots according to the metal layering technology of each device design of the MPW shuttle when the common fabrication process is complete, in which one child lot comprises the coinsurance wafers, and the other child lots are processed with different metal layering fabrication processes.

15. (Canceled).

16. (Original): The method of claim 13 further comprising releasing at least one of the coinsurance wafers, and processing it with the metal layering fabrication process corresponding to each original wafer scrapped in the metal layering fabrication process.

17. (Original): The method of claim 13 further comprising delivering respective products of each device design fabricated from the original wafers to corresponding clients.

18. (Original): The method of claim 13 further comprising receiving a request for at least one designated device design after the metal layering fabrication processes.

19. (Original): The method of claim 18 wherein the request is received before a cutoff date of the MPW shuttle.

20. (Original): The method of claim 18 further comprising releasing at least one of the coinsurance wafers for processing with the corresponding metal layering fabrication process when the request is received.

21. (Original): The method of claim 13 further comprising transferring information of the coinsurance wafers to clients via a network.

22. (Original): The method of claim 21 further comprising transferring information of the original wafers corresponding to the respective device designs to the corresponding clients.

23. (Original): The method of claim 13 wherein the metal layering technology is the number of metal layers of each device design.

24. (Original): The method of claim 13 further comprising determining the quantity of coinsurance wafers according to a scrapping rate and the quantity of the original wafers.

25. (Currently Amended): A machine-readable storage medium storing a computer program which when executed causes a computer to perform a method of coinsurance wafer management for use in MPW (multi-project wafer) shuttle service, comprising the steps of:

processing at least one MPW shuttle with a common fabrication process before metal layering, in which the MPW shuttle includes a plurality of original wafers and a quantity of coinsurance wafers;

processing the original wafers with different metal layering fabrication processes according to a metal layering technology of each device design of the MPW shuttle; and
withholding the coinsurance wafers without further fabrication; and
releasing at least one of the coinsurance wafers to replace each original wafer scrapped in the common fabrication process.

26. (Original): The storage medium of claim 25 further comprising splitting the MPW shuttle into a plurality of child lots according to the metal layering technology of each device design of the MPW shuttle when the common fabrication process is complete, in which one child lot comprises the coinsurance wafers, and the other child lots are processed with different metal layering fabrication processes.

27. (Canceled).

28. (Original): The storage medium of claim 25 further comprising releasing at least one of the coinsurance wafers for each original wafer scraped in the common fabrication process for processing with the corresponding metal layering fabrication process.

29. (Original): The storage medium of claim 25 further comprising delivering respective products of each device designs fabricated from the original wafers to corresponding clients.

30. (Original): The storage medium of claim 25 further comprising receiving a request for at least one designated device design of the device designs after the metal layering fabrication processes.

31. (Original): The storage medium of claim 30 wherein the request is received before a cutoff date of the MPW shuttle.

32. (Original): The storage medium of claim 30 further comprising releasing at least one of the coinsurance wafers, and processing it with the corresponding metal layering fabrication process when the request is received.

33. (Original): The storage medium of claim 25 further comprising transferring information of the coinsurance wafers to clients via a network.

34. (Original): The storage medium of claim 33 further comprising transferring information of the original wafers corresponding to the respective device designs to the corresponding clients.

35. (Original): The storage medium of claim 25 wherein the metal layering technology is the number of metal layers of each device design.

36. (Original): The storage medium of claim 25 further comprising determining the quantity of coinsurance wafers according to a scrapping rate and the quantity of the original wafers.